

GOOLED

GooLED-LUM-4868 Pin Fin Heat Sink Φ48mm for LumiLEDs

Features VS Benefits

- * The GooLED-LUM-4868 LumiLEDs Pin Fin LED Heat Sinks are specifically designed for luminaires using the LumiLEDs LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 600 to 1,800 lumen.
- * Thermal resistance range Rth 4.35°C/W.
- * Modular design with mounting holes foreseen for direct mounting of LumiLEDs COB series.
- * Diameter 48mm standard height 68mm, Other heights on request.
- * Forged from highly conductive aluminum.

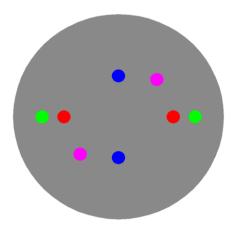
Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of LumiLEDs COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.









LumiLEDs LED Modules directly Mounting Options LumiLEDs COB series.

LUXEON CoB 1202s: L2C5-xxxx1202E0600; LUXEON CoB 1202HD: L2C5-xxxx1202EH600;

With the Zhaga Book 11 holders for the red indicator marks.

TE Connectivity Holder: 2213118-2;

BJB Holder:47.319.6180.50;
Without the holders for the blue indicator marks.

With the Zhaga Book 3 holders for the green indicator marks. TE Connectivity Holder: 2213382-1;

LuXEon CX Plus CoB series.

LUXEON CoB M02: L2C4-xxxx-M02E0900; LUXEON CoB M03: L2C4-xxxx-M03E0900;

With the Zhaga Book 11 holders for the red indicator marks.

With the LEDiL products:

Ronda series: FN15xxx-xx;





Mounting Options and Drawings & Dimensions

Example:GooLED-LUM-4868-B-1,2

Example:GooLED-LUM-48 1 - 2

xample:GooLED-LUM-48

1 Height (mm)
2 Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

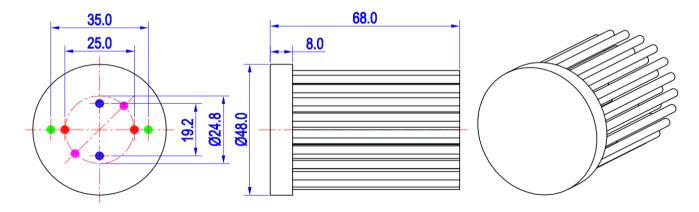
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
			Ronda series	Olivia series	INCEAD	DEPTH	DISTANCE
1	LUXEON 1202s; LUXEON 1202HD;	/		/	М3	6.5mm	19.2mm/ 2-@180°
2	LUXEON CoB M02; LUXEON CoB M03;	BJB Holder 47.319.6104.50	FN15xxx-xx;		М3	6.5mm	25.0mm/ 2-@180°
	LUXEON 1202s; LUXEON 1202HD;	BJB Holder 47.319.6180.50					
		TE Holder 2213118-2					
3	LUXEON 1202; LUXEON 1203;	/			М3	6.5mm	24.8mm/ 2-@180°
4		TE Holder 2213382-1			М3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)



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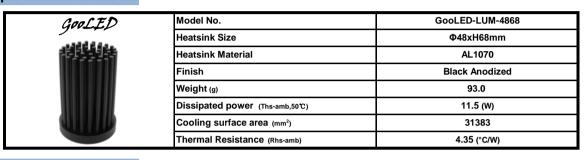
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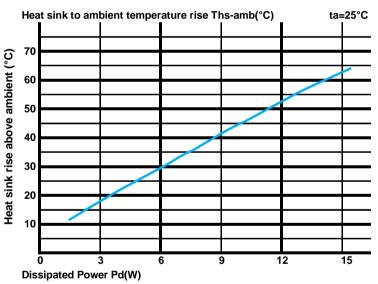
The product deta table



The thermal data table

- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (1-\eta L)$.
- Pd Dissipated power; Pe Electrical power; $\eta L = \text{Light effciency of the LED module}$;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)		
		GooLED-LUM-4868			
Dissipated Power Pd(W)	3.0	6.00	18.0		
	6.0	4.83	29.0		
	9.0	4.56	41.0		
	12.0	4.33	52.0		
	15.0	4.13	62.0		



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.
- T_{case}
 T_{beatsink-base}
 T_{ambient}
 T_{junctio}
 R_{junction-case}
 R_{interface (TIM)}
 R_{heatsink-ambient}
 T_{ambient}
- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- $\theta\,$ Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface}}(TIM)$ ["CM], the thermal resistance with the heat sink is $R_{\text{heatsink-ambient}}$ ["CM], and the ambient temperature is T_{ambient} ["C].
- *Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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